

## CMOS-CCD 1H Delay Line for NTSC with PLL

### Description

The CXL5005M/P are general-purpose CCD delay line ICs which provide 1H delay time of NTSC.

### Features

- Low power consumption 90mW (Typ.)
- Small size package (14-pin SOP, DIP)
- Low differential gain DG = 3% (Typ.)
- Input signal amplitude 180 IRE (= 1.28Vp-p, max.)
- Low input clock amplitude operation 200mVp-p (Min.)
- Built-in triple PLL circuit
- Built-in peripheral circuits (clock driver, timing generator, auto-bias and output circuits)

### Functions

- 680-bit CCD register
- Clock drivers
- Autobias circuit
- Sync tip clamp circuit
- Sample-and-hold circuit
- PLL (triple)

### Structure

CMOS-CCD

### Absolute Maximum Ratings (Ta = 25°C)

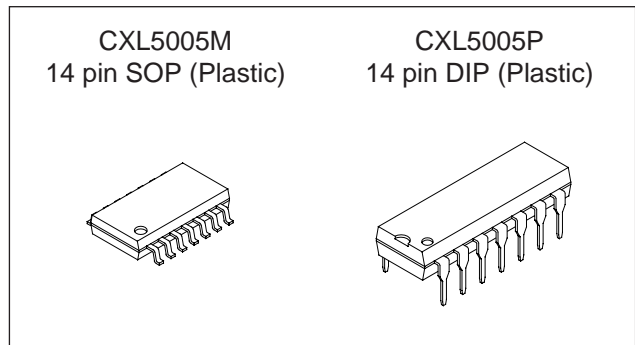
• Supply voltage	V <sub>DD</sub>	11	V
• Supply voltage	V <sub>CL</sub>	6	V
• Operating temperature	T <sub>opr</sub>	-10 to +60	°C
• Storage temperature	T <sub>stg</sub>	-55 to +150	°C
• Allowable power dissipation	P <sub>D</sub>		
	CXL5005M	400	mW
	CXL5005P	800	mW

### Recommended Operating Conditions

Supply voltage	V <sub>DD</sub>	9 ± 5%	V
	V <sub>CL</sub>	5 ± 5%	V

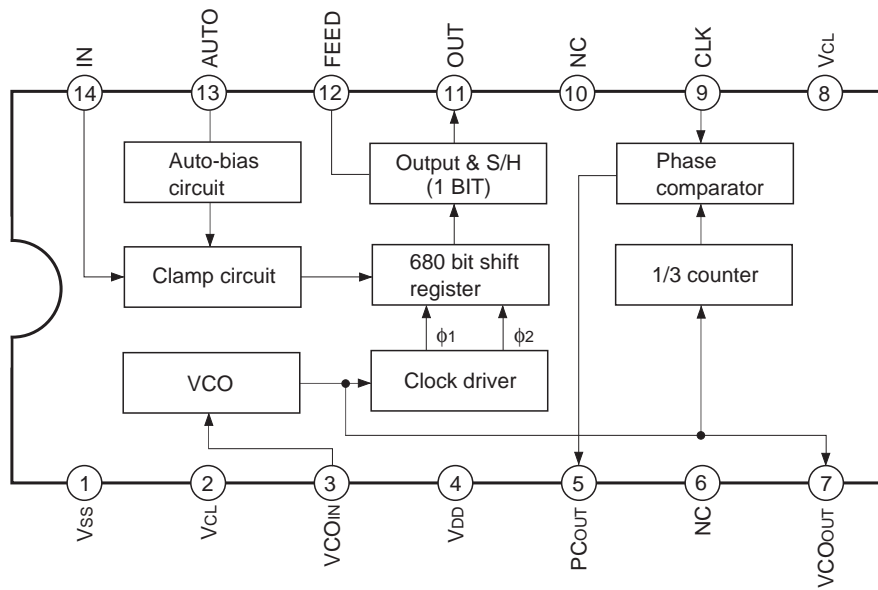
### Recommended Clock Conditions

- Input clock amplitude V<sub>CLK</sub> 200mVp-p to 1.0Vp-p (300mVp-p typ.)
- Clock frequency f<sub>CLK</sub> 3.579545MHz



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**Block Diagram and Pin configuration**



**Pin Description**

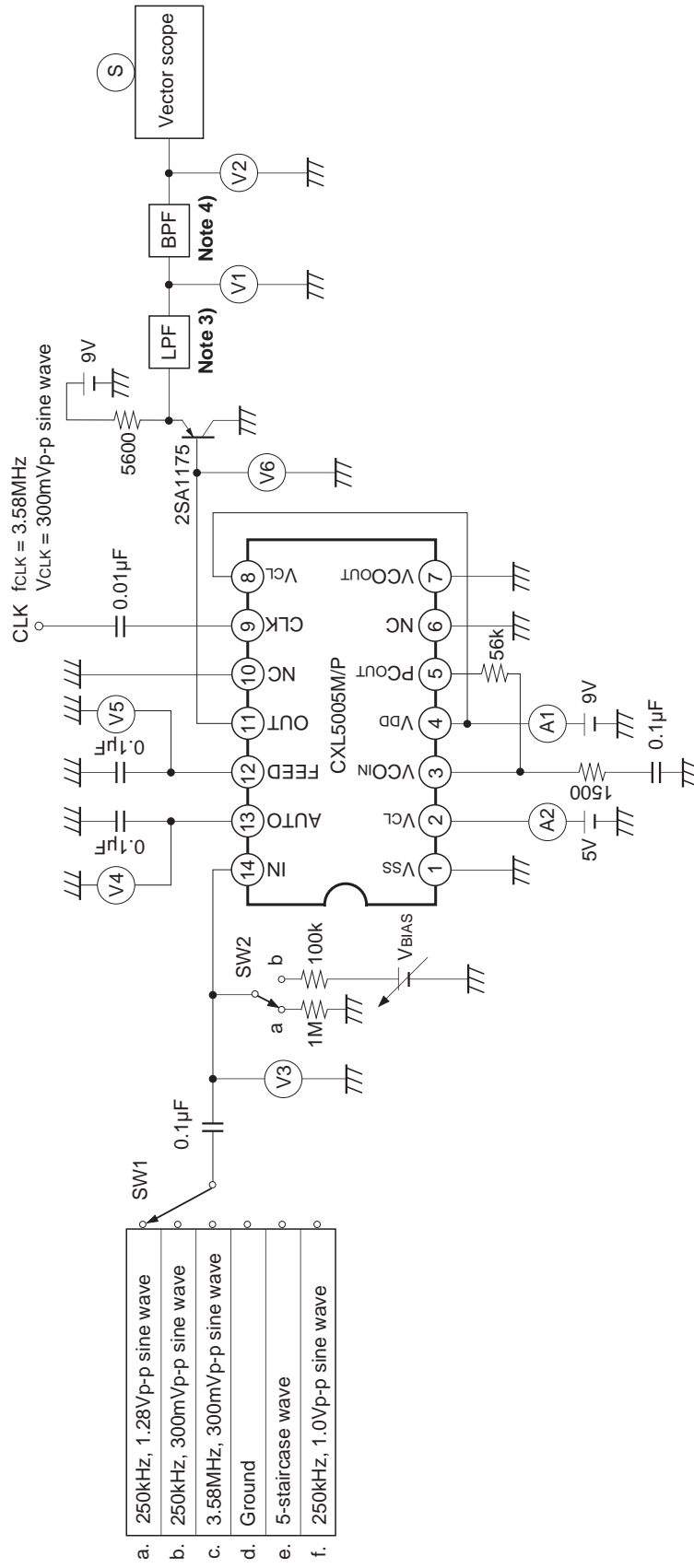
Pin No.	Symbol	Description	Impedance [ $\Omega$ ]
1	VSS	GND	
2	VCL	5V power supply	
3	VCOIN	VCO input	> 100k
4	VDD	9V power supply	
5	PCOUT	Phase comparator output	$\approx$ 5k
6	NC		
7	VCOOUT	VCO output	$\approx$ 5k
8	VCL	5V power supply	
9	CLK	Clock input	$\approx$ 5k
10	NC		
11	OUT	Signal output	600 to 1k
12	FEED	Feedback DC output	> 100k
13	AUTO	Autobias DC output	$\approx$ 10k
14	IN	Signal input	> 100k

## Electrical Characteristics

( $T_a = 25^\circ\text{C}$ ,  $V_{DD} = 9.0\text{V}$ ,  $V_{CL} = 5.0\text{V}$ ,  $f_{CLK} = 3.58\text{MHz}$ ,  $V_{CLK} = 300\text{mVp-p}$  sine wave,  
See "Electrical Characteristics Test Circuit")

Item	Symbol	Test condition	SW condition		Measuring point	Min.	Typ.	Max.	Unit
			1	2					
Supply current	I <sub>DD</sub>	250kHz, 1.28Vp-p, sine wave input	a	a	A1	—	4.0	5.0	mA
	I <sub>CL</sub>				A2	—	9.0	12.0	mA
Insertion gain	IG	250kHz, 1.28Vp-p, sine wave input IG = 20 log (Output voltage [Vp-p] / 1.28 [Vp-p])	a	a	V1	-3.0	0.0	3.0	dB
Frequency response	fG	Dissipation at 3.58MHz in relation to 250kHz fG = 20 log (V <sub>3.58MHz</sub> / V <sub>250kHz</sub> ) <b>(Note 1)</b>	b, c	b	V1	-3.0	-2.1	—	dB
Differential gain	DG	5-staircase wave input Y = 140 IRE (= 1.0Vp-p) Measure with vector scope <b>(Note 2)</b>	e	a	S	—	3.0	5.0	%
Differential phase	DP					—	3.0	5.0	deg
Allowable input amplitude	V <sub>IN-AC</sub>		—	—	—	—	—	1.28	Vp-p
Noise	S/N	S: Input = 250kHz, 1.0Vp-p output (Vp-p)	f	a	V2	55	60	—	dB
		N: Input = DC GND output (V <sub>rms</sub> )	d	a					
DC output voltage	V <sub>IN-DC</sub>		d	a	V3	3.5	5.0	6.5	V
	V <sub>AUTO-DC</sub>				V4	3.5	5.0	6.5	V
	V <sub>FEED-DC</sub>	250kHz, 1.28Vp-p, sine wave input	a	a	V5	1.3	2.3	3.3	V
	V <sub>OUT-DC</sub>				V6	1.7	2.7	3.7	V

Electrical Characteristics Test Circuit

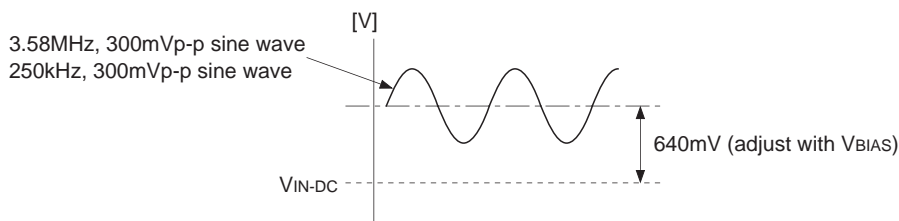


**Note 1) Frequency response test condition**

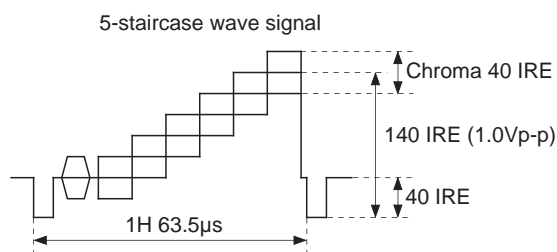
$V_{3.58\text{MHz}}$  (Output signal voltage [Vp-p] at 3.58MHz input)

$V_{250\text{kHz}}$  (Output signal voltage [Vp-p] at 250kHz input)

Set Pin 14 (IN) voltage [V] =  $V_{\text{IN-DC}} + 640\text{mV}$ .

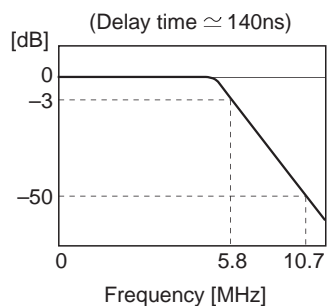


**Note 2) Differential gain and differential phase test condition**

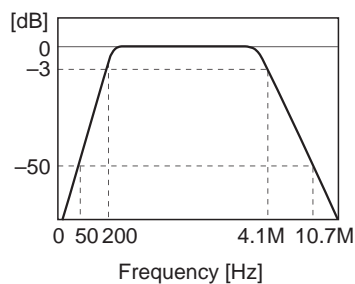


DG and DP are measured at output S point by vector scope.

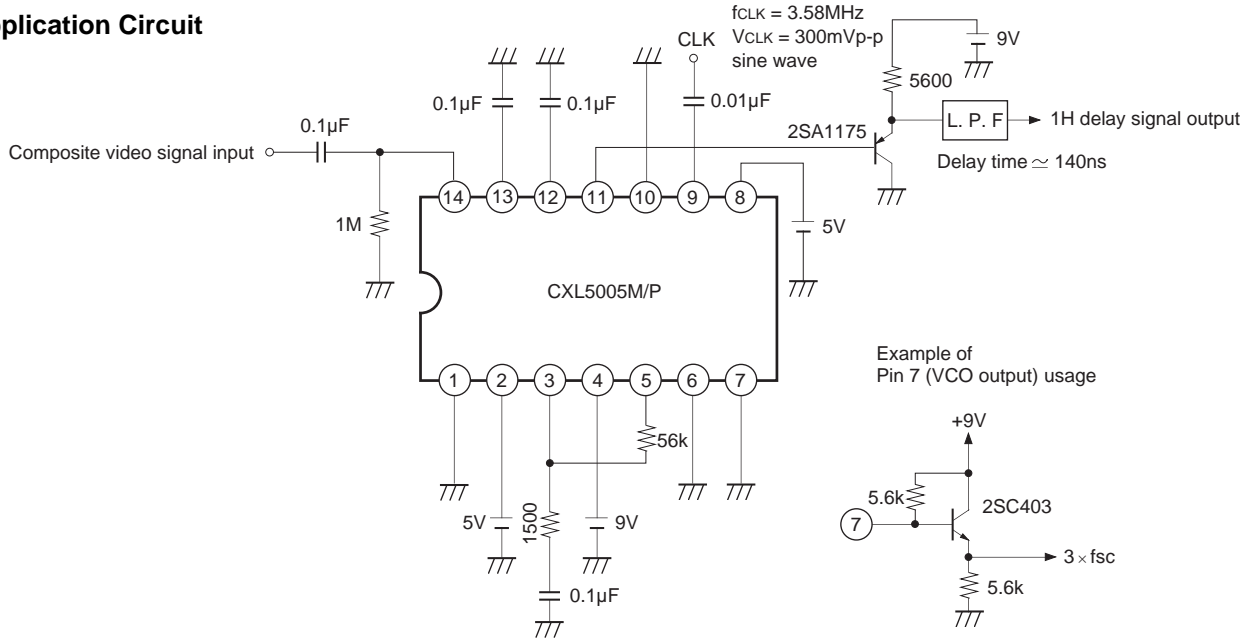
**Note 3) LPF frequency response**



**Note 4) BPF frequency response**

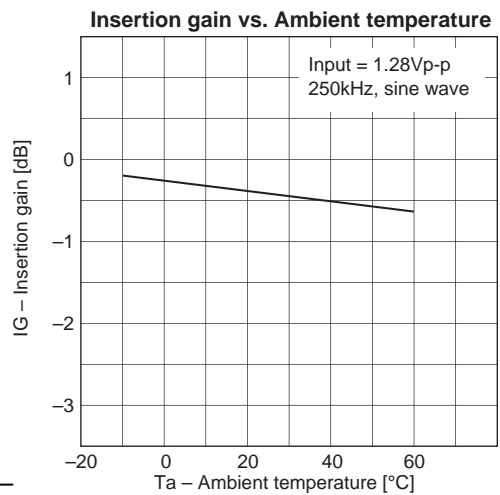
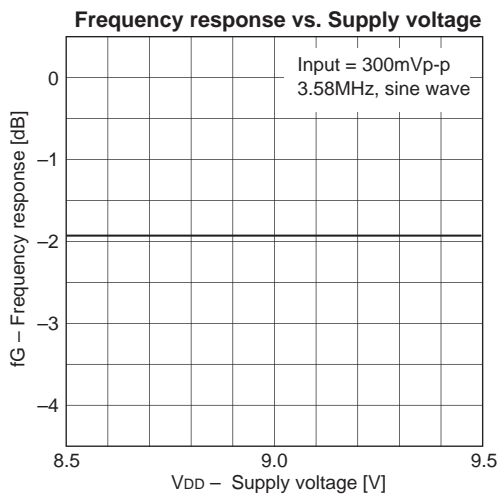
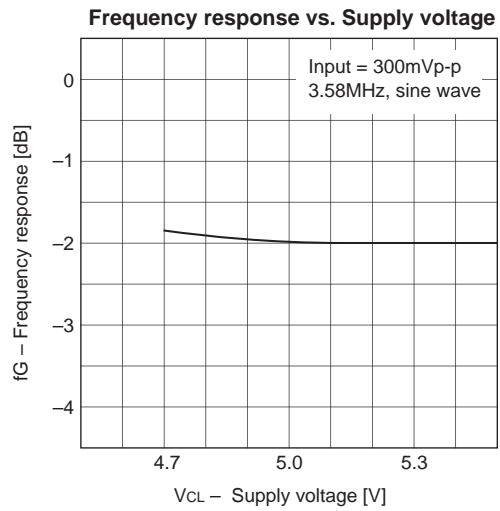
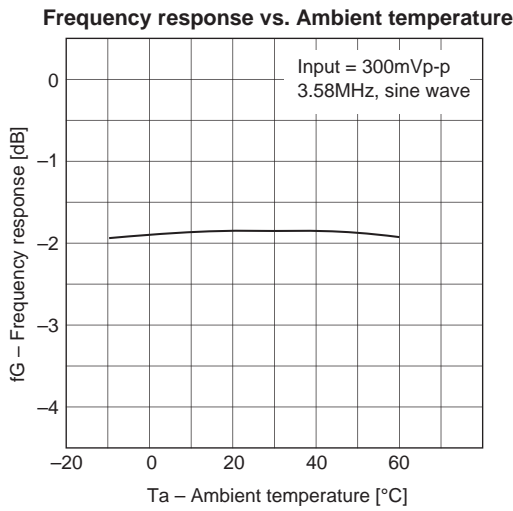


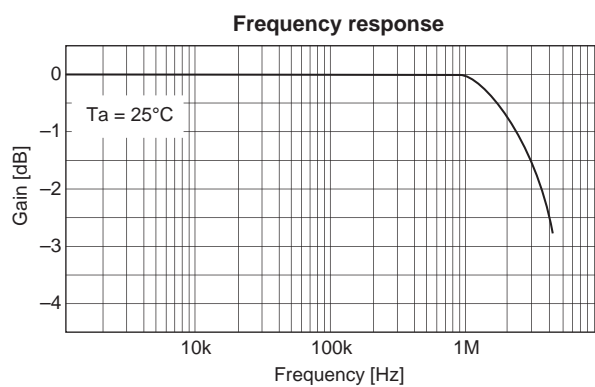
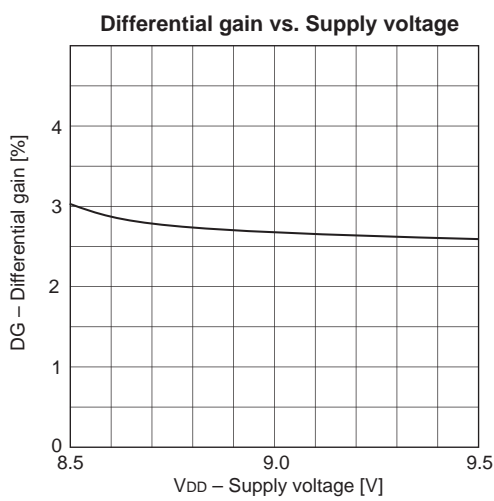
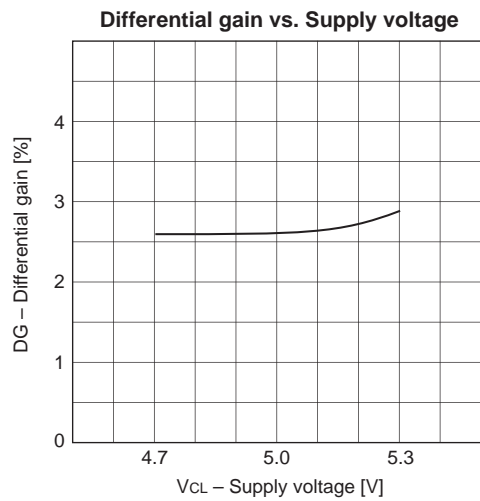
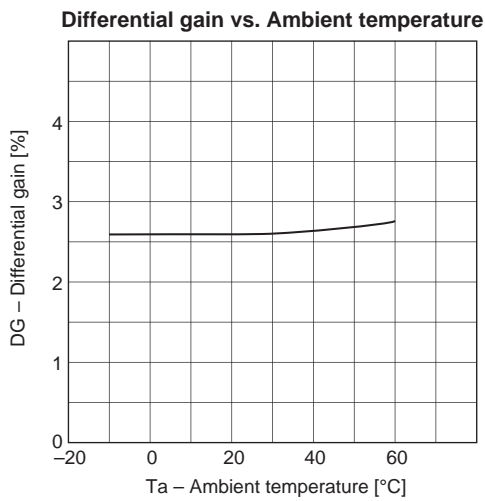
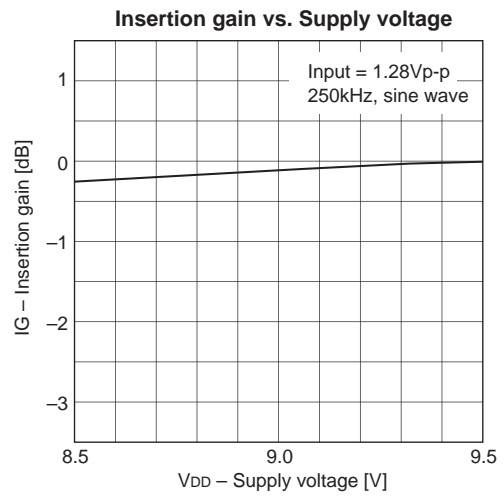
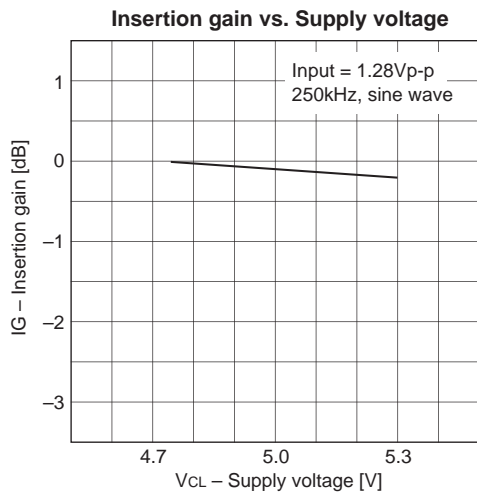
Application Circuit



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Example of Representative Characteristics

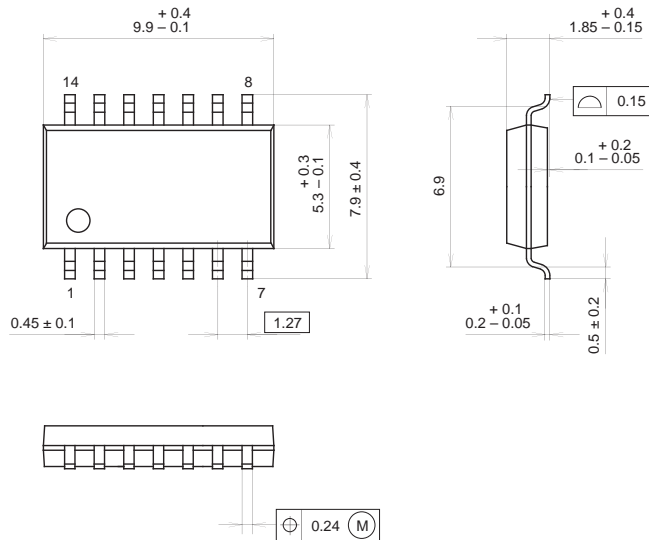




Package Outline Unit: mm

CXL5005M

14PIN SOP (PLASTIC)



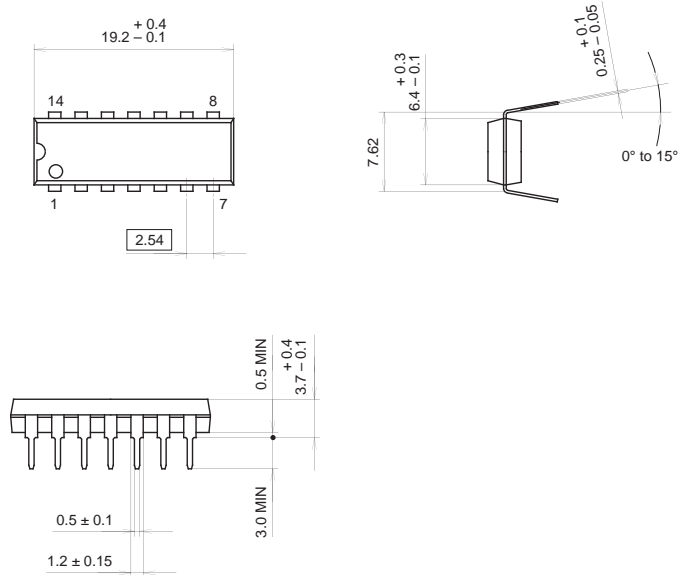
PACKAGE STRUCTURE

SONY CODE	SOP-14P-L01
EIAJ CODE	SOP014-P-0300
JEDEC CODE	

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.2g

CXL5005P

14PIN DIP (PLASTIC)



PACKAGE STRUCTURE

SONY CODE	DIP-14P-01
EIAJ CODE	DIP014-P-0300
JEDEC CODE	Similar to MO-001-AH

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.9g